

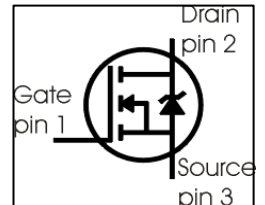
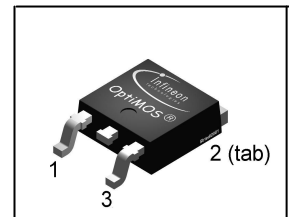
OptiMOS® Power-Transistor
Feature

- N-Channel
- Enhancement mode
- Logic Level
- Excellent Gate Charge x $R_{DS(on)}$ product (FOM)
- Superior thermal resistance
- 175°C operating temperature
- Avalanche rated
- dv/dt rated

Product Summary

V_{DS}	30	V
$R_{DS(on)}$	6.7	m Ω
I_D	30	A

P- TO252 -3-11



Type	Package	Ordering Code	Marking
SPD30N03S2L-07	P- TO252 -3-11	Q67042-S4091	2N03L07

Maximum Ratings, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current ¹⁾ $T_C=25^\circ\text{C}$	I_D	30 30	A
Pulsed drain current $T_C=25^\circ\text{C}$	$I_{D \text{ puls}}$	120	
Avalanche energy, single pulse $I_D=30 \text{ A}$, $V_{DD}=25\text{V}$, $R_{GS}=25\Omega$	E_{AS}	250	mJ
Repetitive avalanche energy, limited by $T_{jmax}^{2)}$	E_{AR}	13	
Reverse diode dv/dt $I_S=30\text{A}$, $V_{DS}=24\text{V}$, $di/dt=200\text{A}/\mu\text{s}$, $T_{jmax}=175^\circ\text{C}$	dv/dt	6	kV/ μs
Gate source voltage	V_{GS}	± 20	V
Power dissipation $T_C=25^\circ\text{C}$	P_{tot}	136	W
Operating and storage temperature	T_j, T_{stg}	-55... +175	$^\circ\text{C}$
IEC climatic category; DIN IEC 68-1		55/175/56	

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - case	R_{thJC}	-	0.7	1.1	K/W
Thermal resistance, junction - ambient, leaded	R_{thJA}	-	-	100	
SMD version, device on PCB:	R_{thJA}				
@ min. footprint		-	-	75	
@ 6 cm ² cooling area ³⁾		-	-	50	

Electrical Characteristics, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain-source breakdown voltage $V_{GS}=0V, I_D=1mA$	$V_{(BR)DSS}$	30	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D=85\mu A$	$V_{GS(th)}$	1.2	1.6	2	
Zero gate voltage drain current $V_{DS}=30V, V_{GS}=0V, T_j=25^\circ C$ $V_{DS}=30V, V_{GS}=0V, T_j=125^\circ C$	I_{DSS}	-	0.01 10	1 100	μA
Gate-source leakage current $V_{GS}=20V, V_{DS}=0V$	I_{GSS}	-	1	100	
Drain-source on-state resistance $V_{GS}=4.5V, I_D=30A$	$R_{DS(on)}$	-	7.4	9.8	m Ω
Drain-source on-state resistance $V_{GS}=10V, I_D=30A$	$R_{DS(on)}$	-	5.3	6.7	

¹Current limited by bondwire ; with an $R_{thJC} = 1.1K/W$ the chip is able to carry $I_D= 111A$ at $25^\circ C$, for detailed information see app.-note ANPS071E available at www.infineon.com/optimos

²Defined by design. Not subject to production test.

³Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.

Electrical Characteristics

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic Characteristics

Transconductance	g_{fs}	$V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$, $I_D = 30A$	29	58	-	S
Input capacitance	C_{iss}	$V_{GS} = 0V$, $V_{DS} = 25V$, $f = 1MHz$	-	1900	2530	pF
Output capacitance	C_{oss}		-	740	990	
Reverse transfer capacitance	C_{rss}		-	180	270	
Gate resistance	R_G		-	2.3	-	Ω
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 15V$, $V_{GS} = 10V$, $I_D = 15A$, $R_G = 3.6\Omega$	-	8	10	ns
Rise time	t_r		-	17	26	
Turn-off delay time	$t_{d(off)}$		-	62	77.5	
Fall time	t_f		-	47	59	

Gate Charge Characteristics

Gate to source charge	Q_{gs}	$V_{DD} = 24V$, $I_D = 30A$	-	6	8	nC
Gate to drain charge	Q_{gd}		-	18	27	
Gate charge total	Q_g	$V_{DD} = 24V$, $I_D = 30A$, $V_{GS} = 0$ to $10V$	-	51	68	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 24V$, $I_D = 30A$	-	3.1	-	V

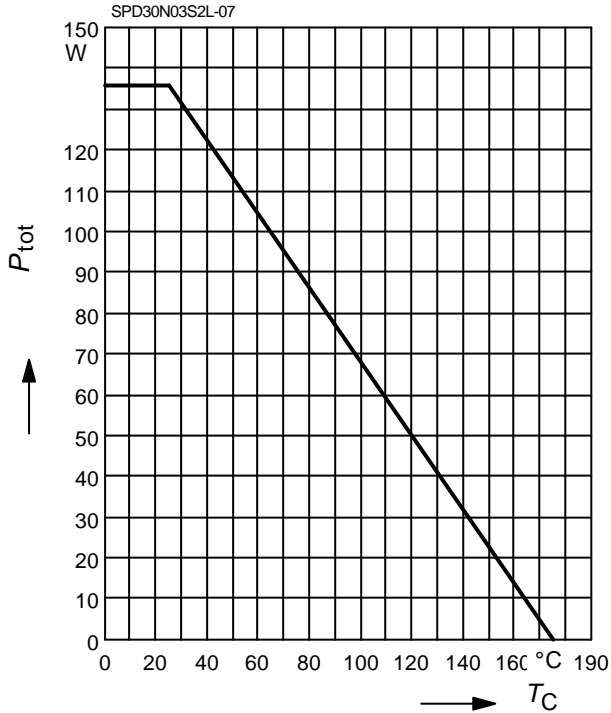
Reverse Diode

Inverse diode continuous forward current	I_S	$T_C = 25^\circ C$	-	-	30	A
Inv. diode direct current, pulsed	I_{SM}		-	-	120	
Inverse diode forward voltage	V_{SD}	$V_{GS} = 0V$, $I_F = 30A$	-	0.9	1.3	V
Reverse recovery time	t_{rr}	$V_R = 15V$, $I_F = I_S$, $di_F/dt = 100A/\mu s$	-	41	51	ns
Reverse recovery charge	Q_{rr}		-	46	58	

1 Power dissipation

$P_{tot} = f(T_C)$

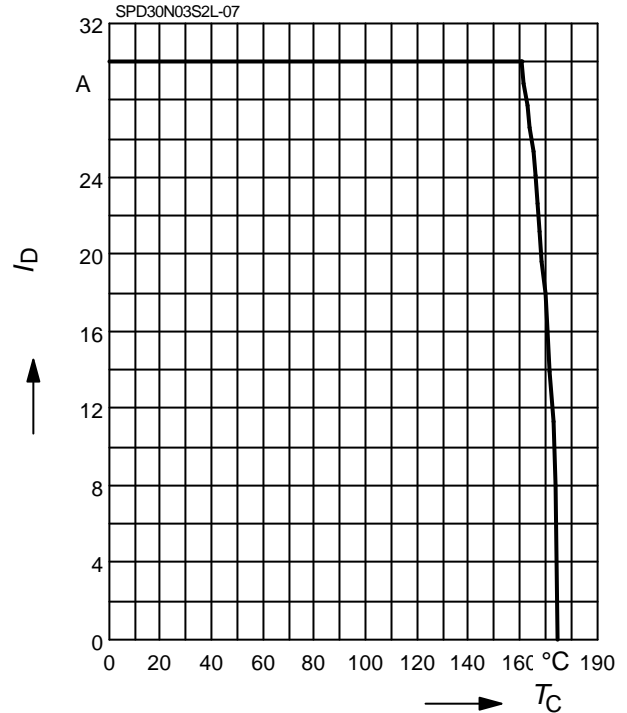
parameter: $V_{GS} \geq 4\text{ V}$



2 Drain current

$I_D = f(T_C)$

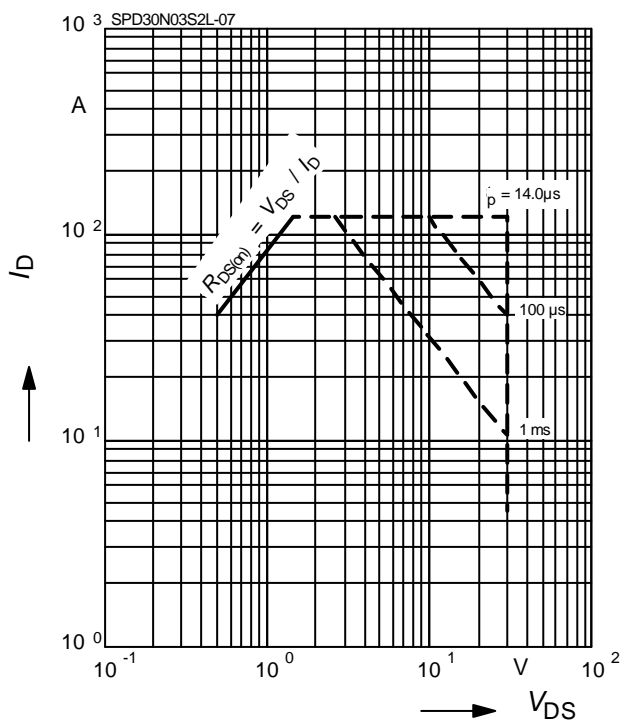
parameter: $V_{GS} \geq 10\text{ V}$



3 Safe operating area

$I_D = f(V_{DS})$

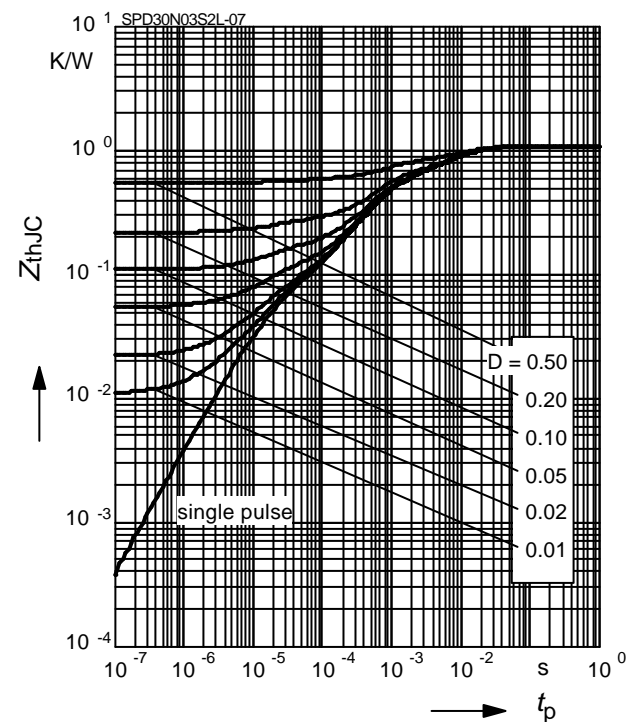
parameter: $D = 0, T_C = 25\text{ °C}$



4 Max. transient thermal impedance

$Z_{thJC} = f(t_p)$

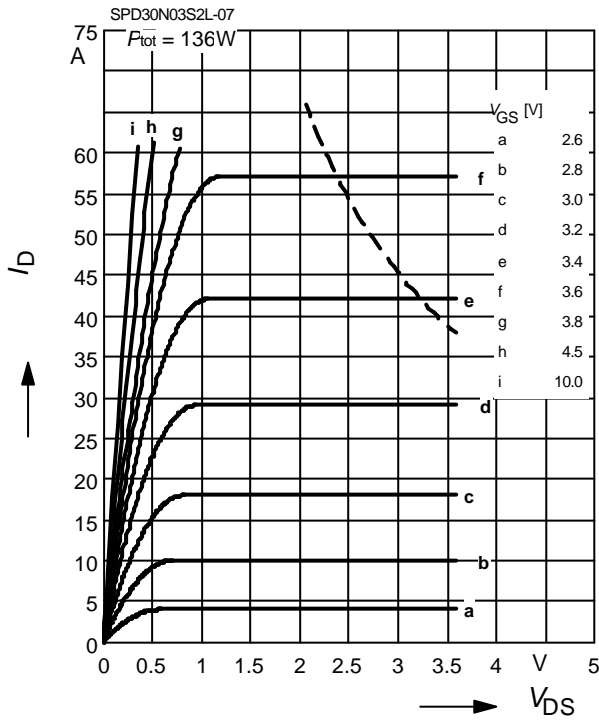
parameter: $D = t_p/T$



5 Typ. output characteristic

$I_D = f(V_{DS}); T_J = 25^\circ\text{C}$

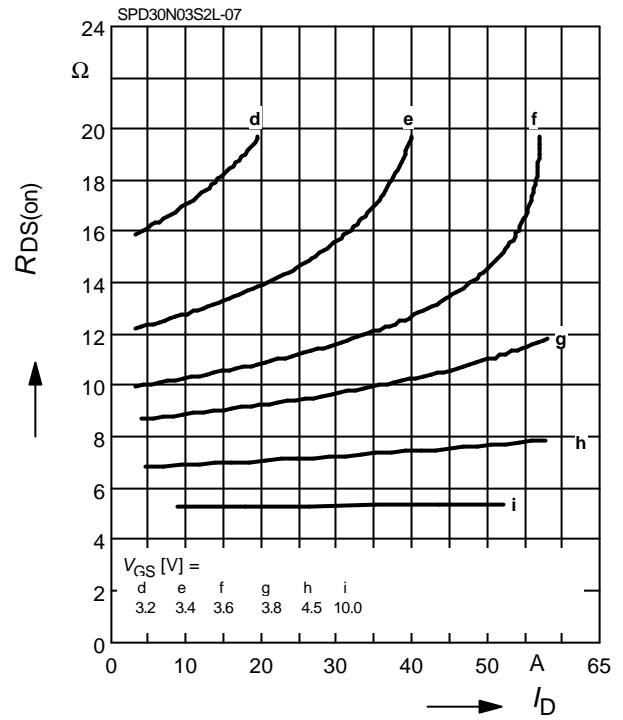
parameter: $t_p = 80 \mu\text{s}$



6 Typ. drain-source on resistance

$R_{DS(on)} = f(I_D)$

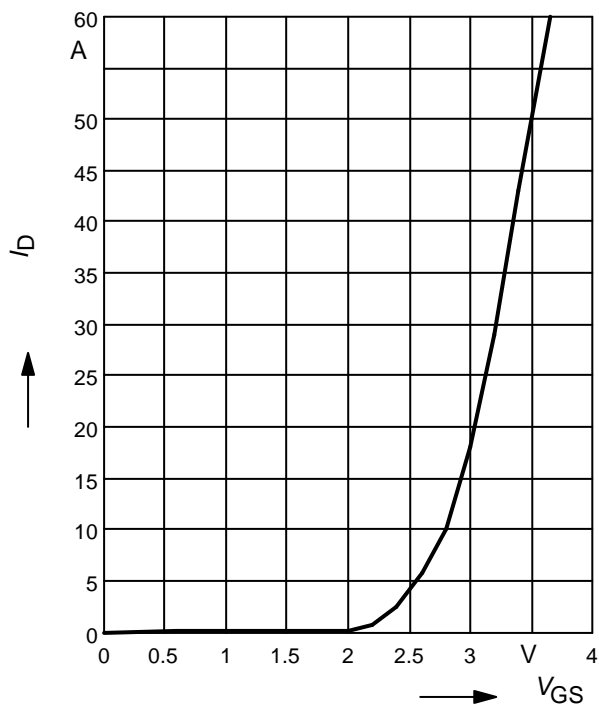
parameter: V_{GS}



7 Typ. transfer characteristics

$I_D = f(V_{GS}); V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$

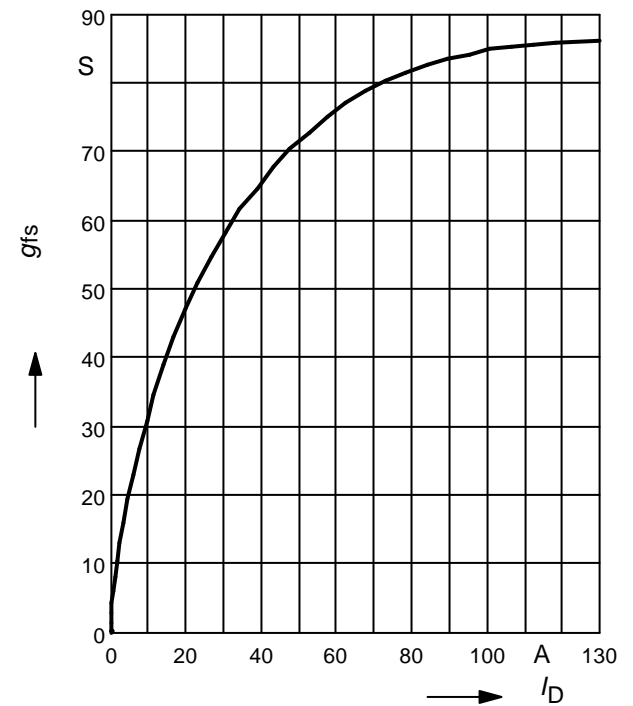
parameter: $t_p = 80 \mu\text{s}$



8 Typ. forward transconductance

$g_{fs} = f(I_D); T_J = 25^\circ\text{C}$

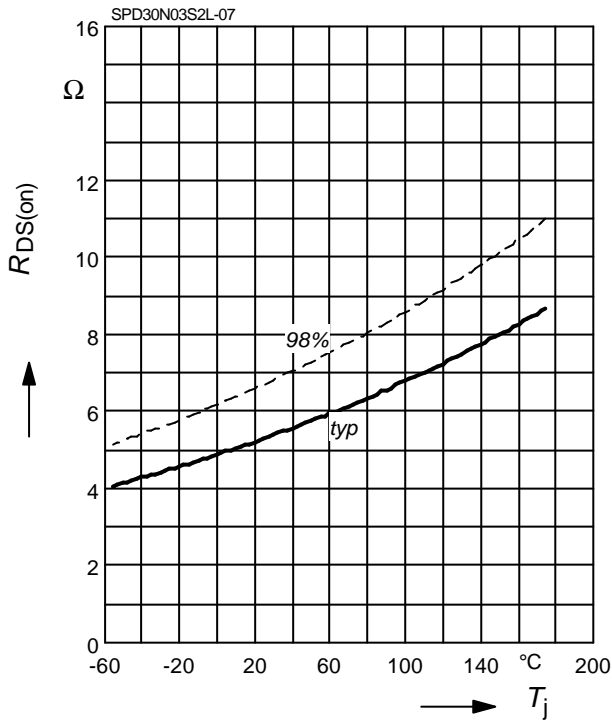
parameter: g_{fs}



9 Drain-source on-state resistance

$$R_{DS(on)} = f(T_j)$$

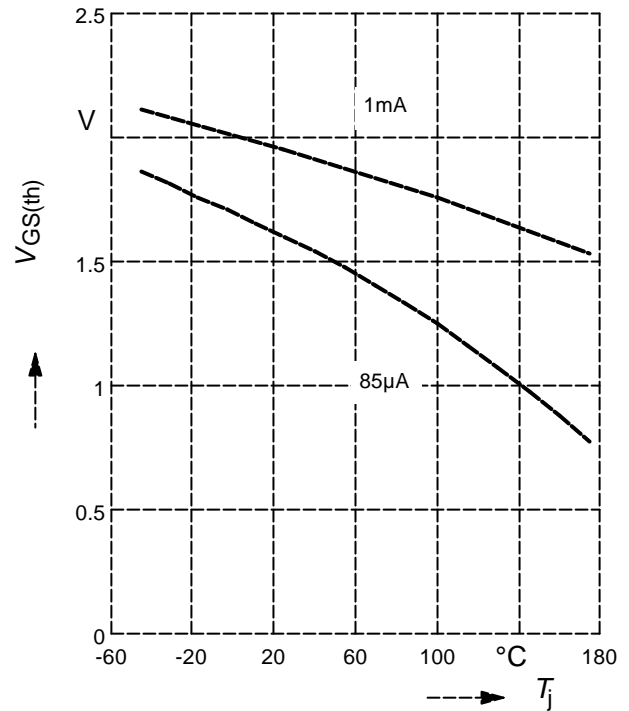
parameter : $I_D = 30\text{ A}$, $V_{GS} = 10\text{ V}$



10 Typ. gate threshold voltage

$$V_{GS(th)} = f(T_j)$$

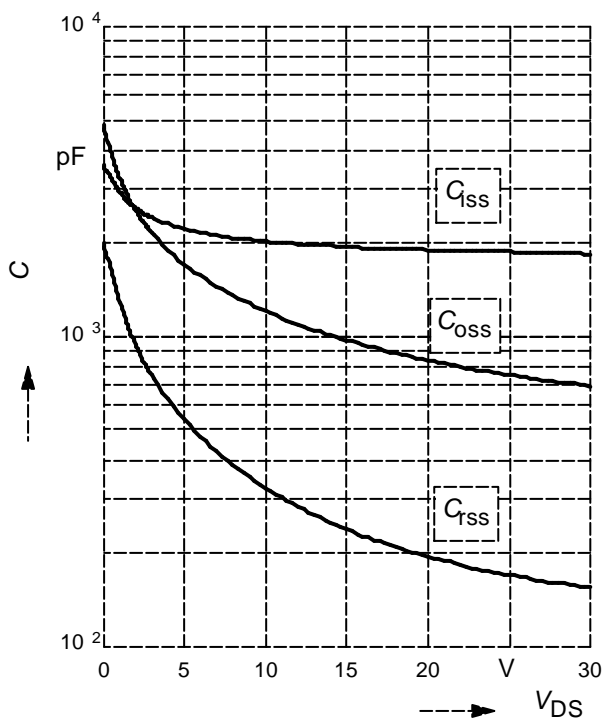
parameter: $V_{GS} = V_{DS}$



11 Typ. capacitances

$$C = f(V_{DS})$$

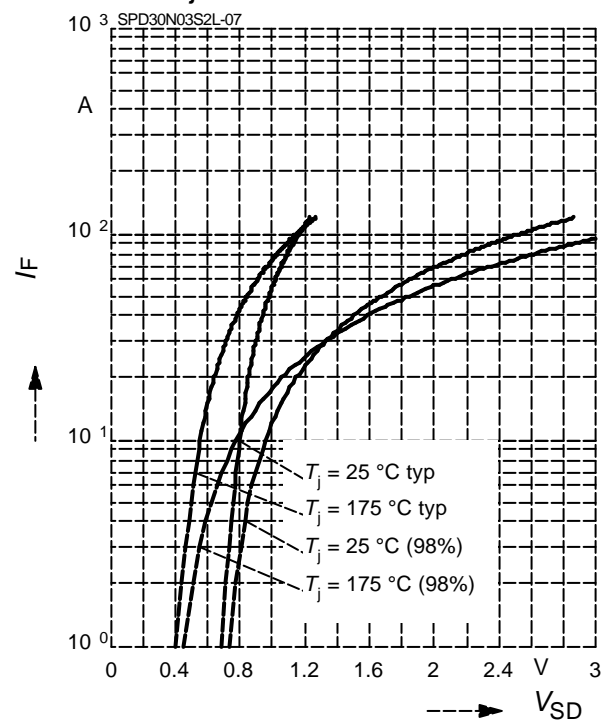
parameter: $V_{GS}=0\text{V}$, $f=1\text{ MHz}$



12 Forward character. of reverse diode

$$I_F = f(V_{SD})$$

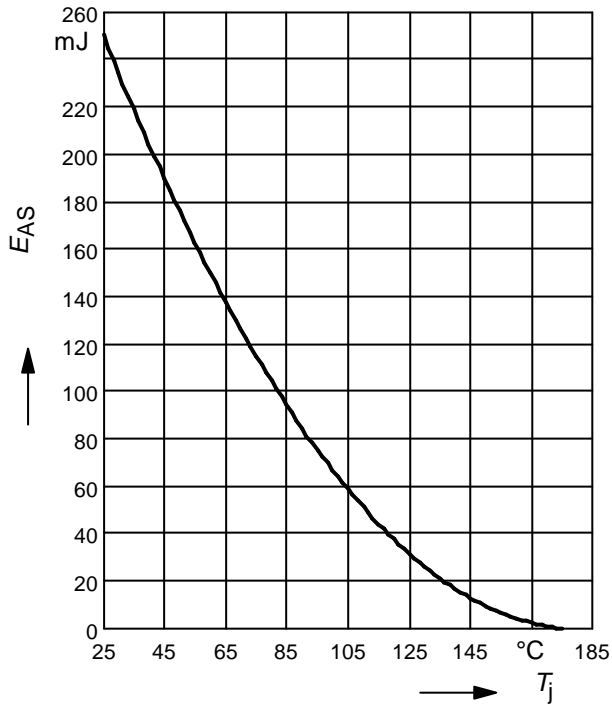
parameter: T_j , $t_p = 80\text{ }\mu\text{s}$



13 Typ. avalanche energy

$$E_{AS} = f(T_j)$$

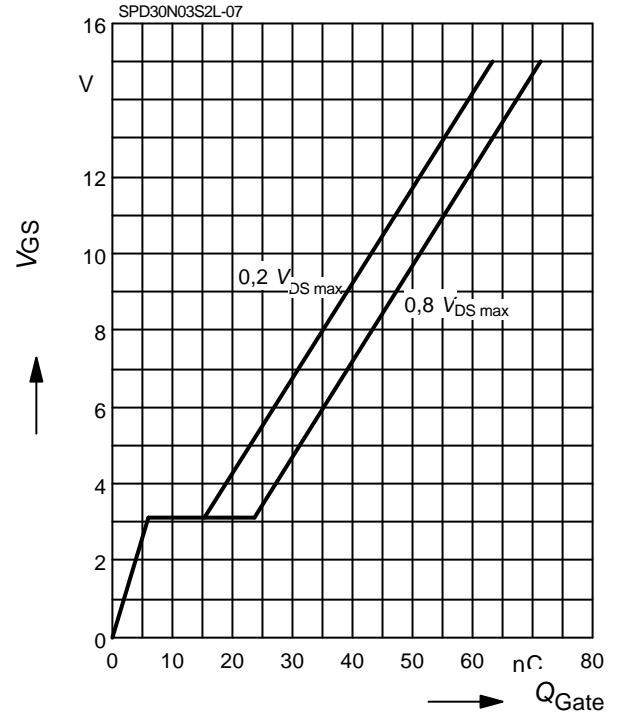
par.: $I_D = 30\text{ A}$, $V_{DD} = 25\text{ V}$, $R_{GS} = 25\ \Omega$



14 Typ. gate charge

$$V_{GS} = f(Q_{Gate})$$

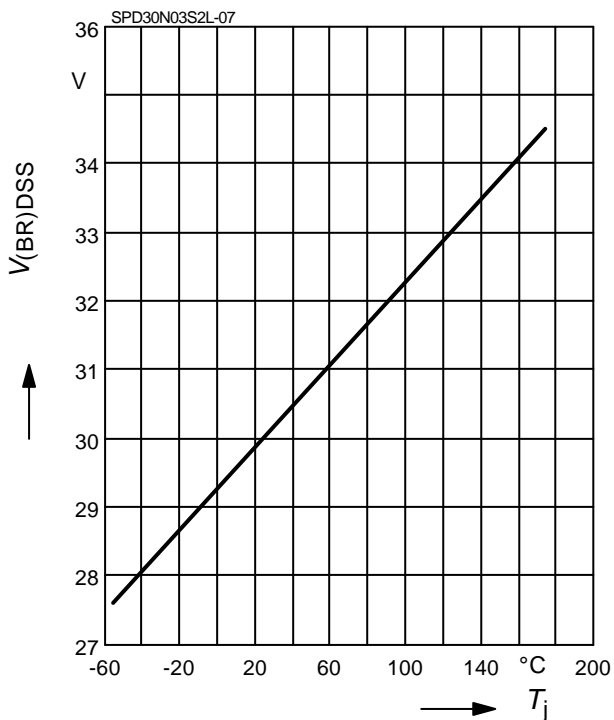
parameter: $I_D = 30\text{ A}$ pulsed



15 Drain-source breakdown voltage

$$V_{(BR)DSS} = f(T_j)$$

parameter: $I_D = 10\text{ mA}$



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